

Title (en)

METHOD FOR JOINING NANOLAMINATES BY MEANS OF ELECTRODEPOSITION

Title (de)

VERFAHREN ZUM FÜGEN VON NANOLAMINATEN MITTELS GALVANISCHER METALLABSCHIEDUNG

Title (fr)

PROCÉDÉ D'ASSEMBLAGE DE NANOSTRATIFIÉS PAR ÉLECTRODÉPOSITION

Publication

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Application

**EP 21840495 A 20211215**

Priority

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Abstract (en)

[origin: WO2022129230A1] The invention relates to a method for joining nanolaminates by means of electrodeposition, the nanolaminate being constructed of at least two layers containing different metals or metal alloys and having a joining point in which multiple layers of the nanolaminate are missing and which has at least two mutually opposing side walls and a bottom: - electrodepositing a new layer in the joining point until a layer with an average thickness is produced on the bottom, wherein the average thickness of the new layer is greater on the bottom of the joining point than on the side walls, - repeating the electrodeposition and removing a layer in the joining point, wherein the material of the layer in the joining point is selected according to a material sequence of the adjacent nanolaminate.

IPC 8 full level

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Citation (search report)

See references of WO 2022129230A1

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